FC150 Flip Chip Bonder

The S.E.T FC150 Device Bonder is a precision instrument used to align and bond one or more chip on a substrate, using one of several available techniques.

System Capabilities:

- 1 µm, 3 Post-Bond Accuracy r
- Die Bonding, Flip Chip
- Wafer-to-wafer Bonding Capability up to 100mm Square.
- Force up to 200 kg
- Temperature up to 450°C Independent heating for chip and substrate .
- High Process Flexibility.
- NIL Configuration compatible without loosing the bonding capability